Docket No. **24295/81003**

(Only for new non provisional applications under 37 CFR 1.53(b))

Total Pages in this Submission 70

TO THE COMMISSIONER FOR PATENTS

Mail Stop Patent Application P.O. Box 1450 Alexandria, CA 22313-1450

Chip Testing Within A Multi-Chip Semiconductor Package						رن ان	S. P. 734
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Adi	ian E	<u>.</u> . Oi	ıy				
f a CC	NTI	NUA	TION APPLICATION	, check appropriate box and supply	the requisite information:		_
Co	ntinu	ıatio	on 🗌 Divisional	☐ Continuation-in-part (CIP)	of a prior application No.:	09/666,208	
Which	is a:						
Co	ntinu	uatio	on Divisional	☐ Continuation-in-part (CIP)	of a prior application No.:		
Which				•			
☐ Co	☐ Continuation ☐ Divisional ☐ Continuation-in-part (CIP) of a prior application No.:						
Enclos	ed a	re:					
	_			Application Elements	5		
Filing fee as calculated and transmitted as described below							
2.	\boxtimes	Spe	ecification having	pages and including the follo	owing:		
	a.	\boxtimes	Descriptive Title of th	e Invention			
b. Cross References to Related Applications (if applicable)							
c. Statement Regarding Federally-sponsored Research/Development (if applicable)							
	d.	\boxtimes	Technical Field of Inv	rention			
	e.	\boxtimes	Background of the In	vention			
	f.	\boxtimes	Description of Relate				
	g.	\boxtimes	Brief Summary of the	Invention			
	h.	\boxtimes	Brief Description of the	e Drawings (if filed)			
	i.	\boxtimes	Detailed Description				
	j.	\boxtimes	Claims as Classified	Below			
	k.	\boxtimes	Abstract of the Disclo	sure			

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	Application Elements (continued)									
	3.	\boxtimes	Drawing(s) (when necessary as prescribed by 35 USC 113)							
		a.	Formal Number of Sheets							
		b.	☐ Informal Number of Sheets nine (9)							
	4.	\boxtimes	Oath or Declaration							
		☐ Newly executed (original or copy) ☐ Unexecuted								
¥		b.	Copy from a prior application (37 CFR 1.63(d)) (for continuation/divisional application only)							
		C.	. 🛛 With Power of Attorney 🔲 Without Power of Attorney							
		 DELETION OF INVENTOR(S) Signed statement attached deleting inventor(s) named in the prior application, see 37 C.F.R. 1.63(d)(2) and 1.33(b). 								
	5.		Incorporation By Reference (usable if Box 4b is checked) The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.							
	6.		CR ROM or CD-R in duplicate, large table or Computer Program (Appendix)							
	7.		Application Data Sheet (See 37 CFR 1.76)							
	8.		Nucleotide and/or Amino Acid Sequence Submission (if applicable, all must be included)							
		a.	Computer Readable Form (CRF)							
		b.	. Specification Sequence Listing on:							
			i. CD-ROM or CD-R (2 copies); or							
		ii. Paper								
	c. Statement(s) Verifying Identical Paper and Computer Readable Copy									
	^		Accompanying Application Parts							
	9.		Assignment Papers (cover sheet & documents(s)- copy from parent)							
			37 CRF 3.73(B) Statement (when there is an assignee)							
	11.		English Translation Document (if applicable)							
	12.	\boxtimes	Information Disclosure Statement/PTO-1449							
	13.	\boxtimes								
	14.	\boxtimes	Return Receipt Postcard (MPEP 503) (Should be specifically itemized)							
	15.		Certified Copy of Priority Document(s) (if foreign priority is claimed)							
	16.	\boxtimes	Certificate of Mailing							
			☐ First Class ☐ Express Mail (Specify Label No.): EV 305 258 523 US							

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Total Pages in this Submission 70

		Accompanying Application Parts (Continued)	
	17. 🛛	Additional Enclosures (please identify below):	
•		Notice of Change of Address.	
3			
		*	
		Request That Application Not Be Published To 35 U.S.C. 122(b)(2)	
	18. 🗌	Pursuant to 35 U.S.C. 122(b)(2), Applicant hereby requests that this patent application not be published pursuant to 35 U.S.C. 122(b)(1). Applicant hereby certifies that the invention disclosed in this application has not and will not be subject of an application filed in another country, or under a multilateral international agreement, that requires publication of applications 18 Months after filing of the application.	
		Warning	
		An applicant who makes a request not to publish, but who subsequently files in a foreign country or under a multilateral international agreement specified in 35 U.S.C. 122(b)(2(B)(i), must notify the Director of such filing not later than 45 days after the date of the filing of such foreign or international application. A failure of the applicant to provide such notice within the prescribed period shall result in the application being regarded as abandoned, unless it is shown to the satisfaction of the Director that the delay in submitting the notice was unintentional.	

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Fee	Calc	ulatio	n and	Trans	mittal

CLAIMS AS FILED For # Filed # Allowed # Extra Rate Fee 25 **Total Claims** 20 5 \$9.00 Х \$45.00 Indep. Claims 4 3 \$43.00 \$43.00 х Multiple Dependent Claims (check if applicable) \$0.00 **BASIC FEE** \$385.00 OTHER FEE (specify purpose) \$0.00 **TOTAL FILING FEE** \$ 473.00 A check in the amount of to cover the filing fee is enclosed. ☑ The director is hereby authorized to charge and credit Deposit Account No. 50-1597 as described below. □ Charge the amount of \$473.00 as filing fee. Credit any overpayment. □ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.

Philip W. Woo Attorney of Record Reg. No. 39,880 Signature

Dated: April 15, 2004

pursuant to 37 C.F.R. 1.311(b).

Charge the issue fee set in 37 C.F.R. 1.18 at the mailing address of the Notice of Allowance,

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Adrian E. Ong

Assignee:

Inapac Technology, Inc.

Title:

Chip Testing Within A Multi-Chip Semiconductor Package

Application No.:

09/666,208

Filing Date:

September 21, 2000

Examiner:

Unknown

Group Art Unit:

2814

Docket No.:

M-8705 US

Confirmation No.:

Unknown

San Francisco, California February 24, 2003

COMMISSIONER FOR PATENTS

Washington, D. C. 20231

NOTICE OF CHANGE OF ADDRESS

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

Philip W. Woo

c/o SIDLEY AUSTIN BROWN & WOOD LLP

555 CALIFORNIA STREET

SUITE 5000

SAN FRANCISCO, CA 94104-1715

TEL. (415) 772-1200 FAX (415) 397-4621

Certificate of Mailing

I hereby certifiy that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date

Richard A. Pask

Respectfully submitted,

Philip W. Woo

Attorney of Record

Reg. No. 39,880